FEATURES

- For surface mounted applications
- Glass Passivated Chip Junction
- Fast reverse recovery time
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

Simplified outline SOD-323FLW and symbol

Absolute Maximum Ratings at 25 °C

Parameter	Symbols	1N4148WF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	75	V
Continuous Forward Current	I_F	150	mA
Non-reptitive Peak Forward Surge Current at 1s at 1ms at 1us	I_{FSM}	0.5 1 4	A
Total Power Dissipation	P_{tot}	300	mW
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Characteristics at T_a = 25 °C

Parameter	Symbols	1N4148WF	Units
Reverse BreakdownVoltage at I_R=1μA	$V_{(BR)R}$	75	V
Maximum Forward Voltage at 1 m A at 10 m A at 50 m A at 150 m A	V_F	0.715 0.855 1.00 1.25	V
Peak Reverse Current at V_R=20V T_j=25°C at V_R=75V T_j=25°C at V_R=25V T_j=150°C at V_R=75V T_j=150°C	I_R	0.025 1 30 50	μA
Typical Junction Capacitance f=1MHz,V_R=0V	C_j	2	pF
Maximum Reverse Recovery Time (1)	t_{rr}	4	ns

(1) Measured with I_F=I_R=10mA,I_{rr}=0.1*I_R,R_L=100Ω

Fig.1 Power Derating Curve

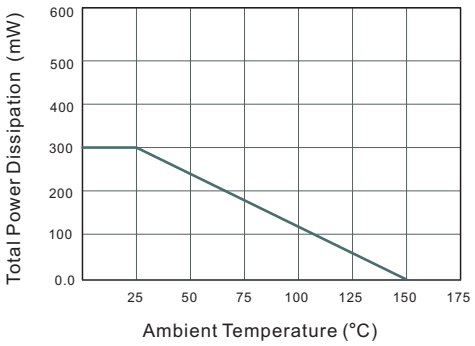


Fig.2 Typical Reverse Characteristics

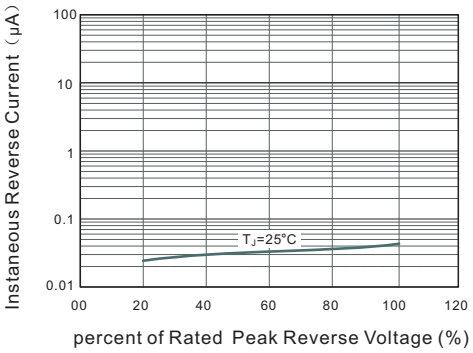


Fig.3 Typical Instaneous Forward Characteristics

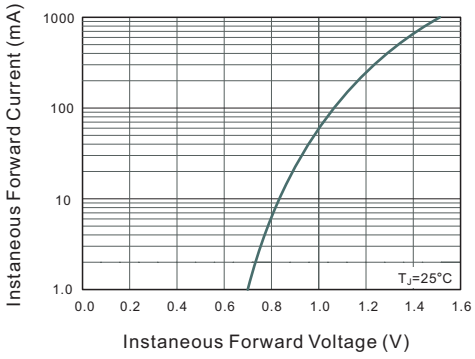
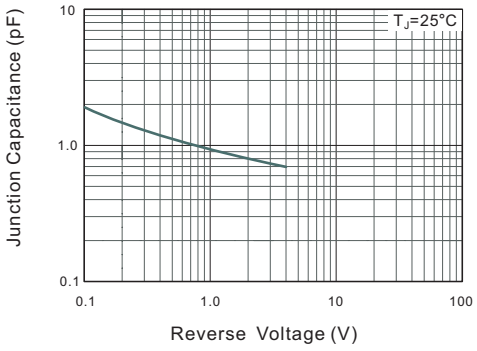
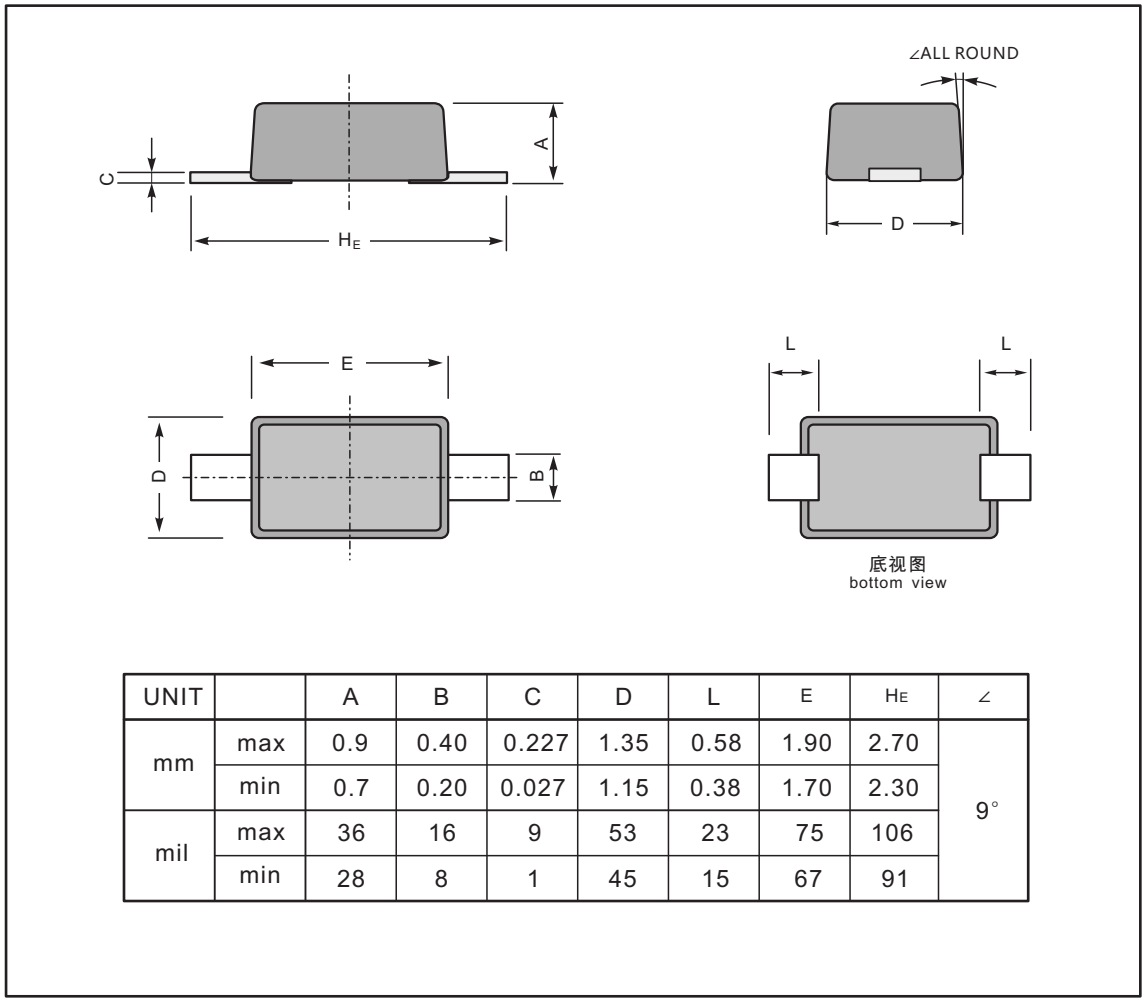


Fig.4 Typical Junction Capacitance



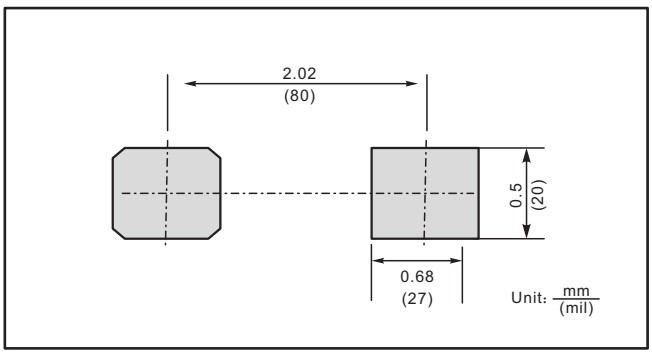
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads SOD-323FLW



UNIT		A	B	C	D	L	E	H_E	∠
mm	max	0.9	0.40	0.227	1.35	0.58	1.90	2.70	9°
	min	0.7	0.20	0.027	1.15	0.38	1.70	2.30	
mil	max	36	16	9	53	23	75	106	
	min	28	8	1	45	15	67	91	

The recommended mounting pad size



Marking

Type number	Marking code
1N4148WF	T4